

A B S T R A C T

A multi-element type chip device of the present invention includes an elongate chip substrate (10), $2n$ pairs of opposed electrodes (12a) [n representing a positive integer] formed on a surface of the chip substrate (10) at a generally constant interval longitudinally of the chip substrate, device elements (131-134) each formed between a respective pair of electrodes, and a protective coating (14-16) formed to cover the device elements (131-134) in a row extending longitudinally of the chip substrate (10). A $(2m-1)$ th device element (131, 133) [m representing a positive integer not exceeding n] as counted from one end (10a) of the chip substrate (10) has a widthwise center which is offset from a widthwise center of a corresponding pair of electrodes (12a) toward the other end (10b) of the chip substrate (10). A $(2m)$ th device element (132, 134) as counted from the one end of the chip substrate (10) has a widthwise center which is offset from a widthwise center of a corresponding pair of electrodes (12a) toward the one end (10a) of the chip substrate (10).